

# MECHANICAL CASE OUTLINE

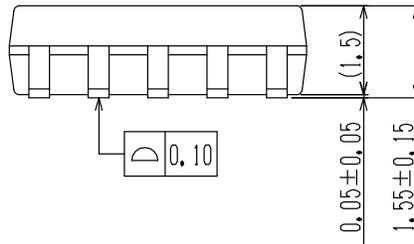
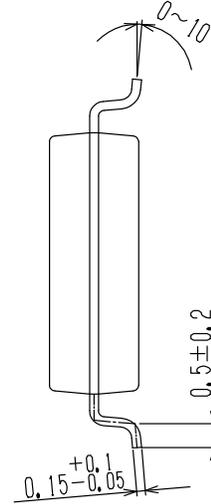
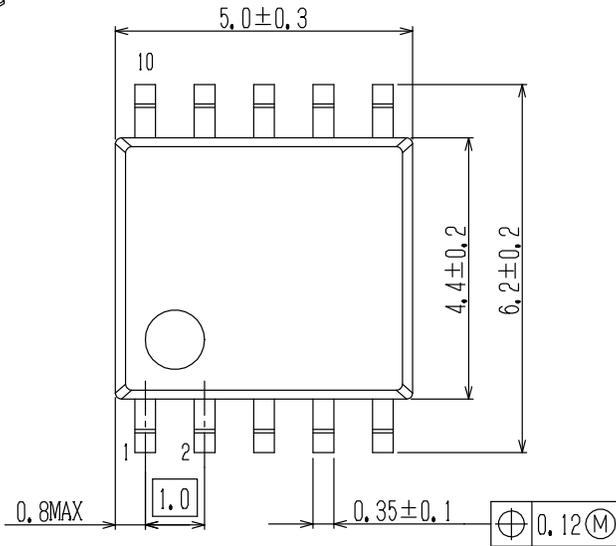
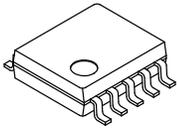
## PACKAGE DIMENSIONS

ON Semiconductor®

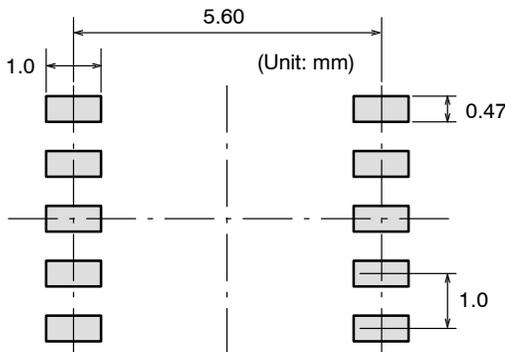


SOIC10W / MFP10SK (225 mil)  
CASE 751DA  
ISSUE A

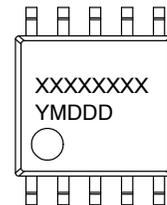
DATE 23 OCT 2013



### SOLDERING FOOTPRINT\*



### GENERIC MARKING DIAGRAM\*



XXXX = Specific Device Code  
Y = Year  
M = Month  
DDD = Additional Traceability Data

NOTE: The measurements are not to guarantee but for reference only.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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<b>DESCRIPTION:</b>	<b>SOIC10W / MFP10SK (225 MIL)</b>	<b>PAGE 1 OF 1</b>

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